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Sofue et al.

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(54) **SEMICONDUCTOR ELEMENT**

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(**) **Term:** **14 Years**

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(51) **LOC (7) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Search** D13/182; 174/524, 174/525; 287/690; 361/752, 758, 820

(56) **References Cited**

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(57) **CLAIM**

The ornamental design for a semiconductor element, as shown and described.

DESCRIPTION

FIG. 1 is a front elevational view showing a semiconductor element according to the present invention; FIG. 2 is a rear elevational view of the element of FIG. 1; FIG. 3 is a top plan view of the element of FIG. 1; FIG. 4 is a bottom plan view of the element of FIG. 1; FIG. 5 is a right side elevational view of the element of FIG. 1, the left side elevational view being a mirror image of the right side elevational view; and, FIG. 6 is a top front perspective view of the element of FIG. 1.

1 Claim, 3 Drawing Sheets

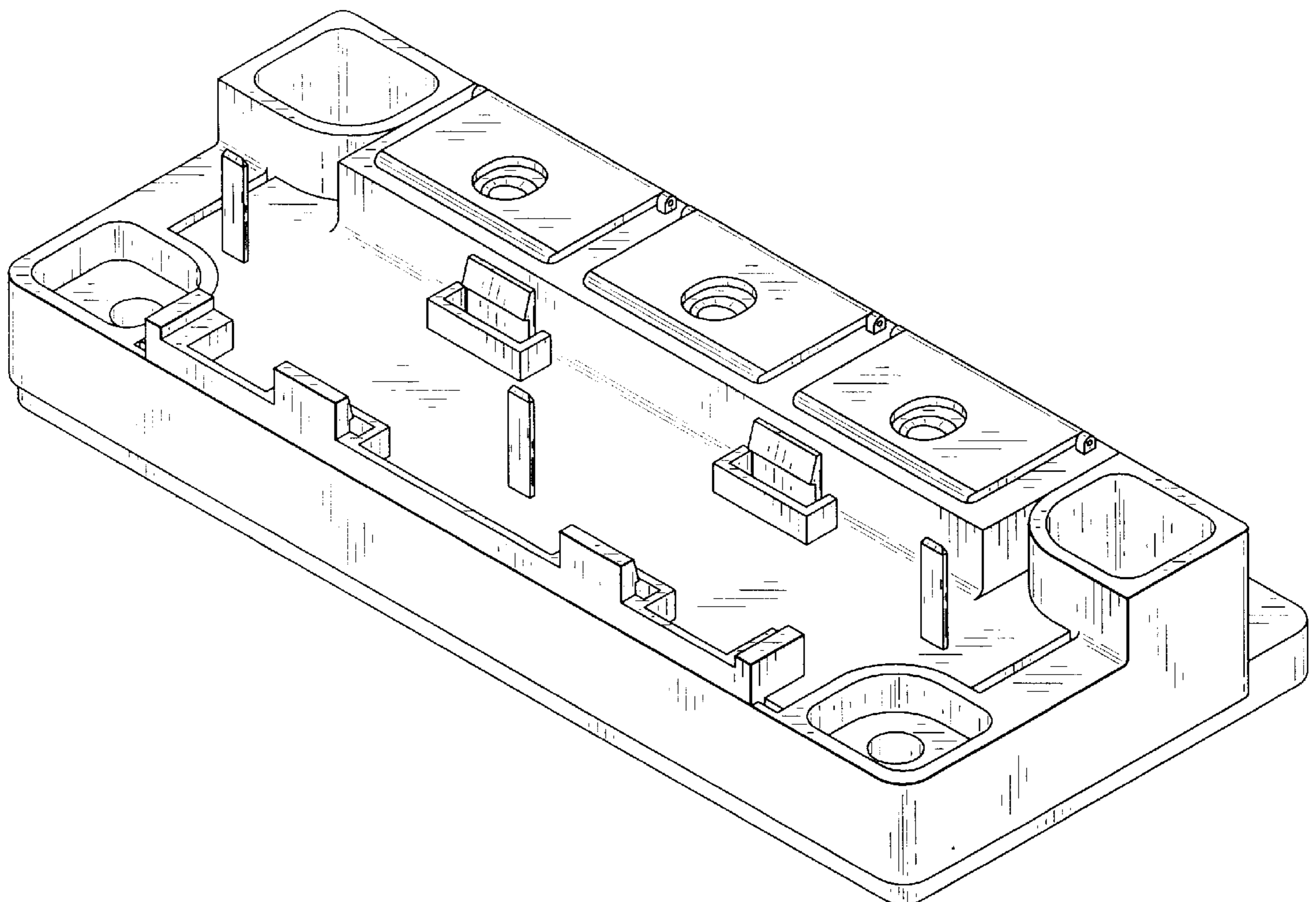


FIG. 1

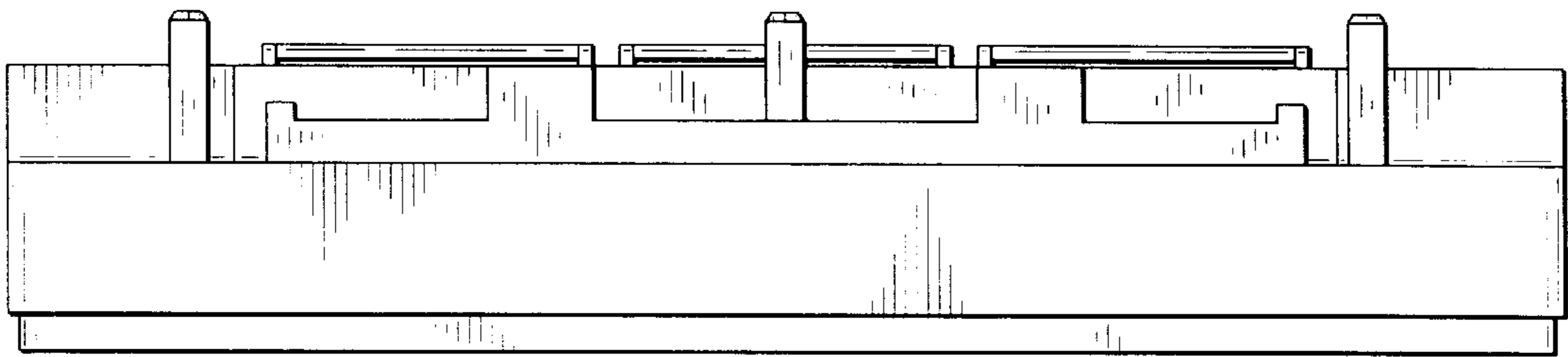


FIG. 2

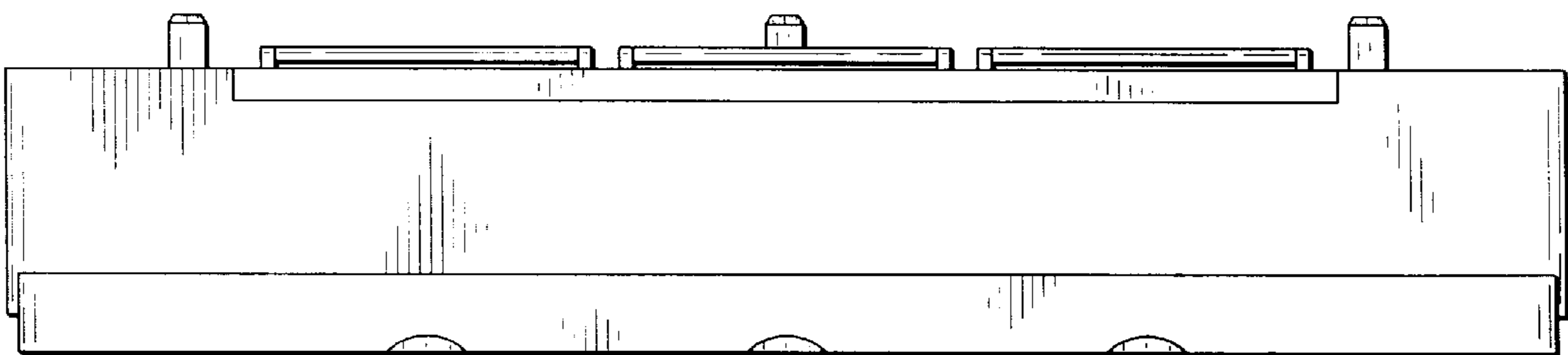


FIG. 3

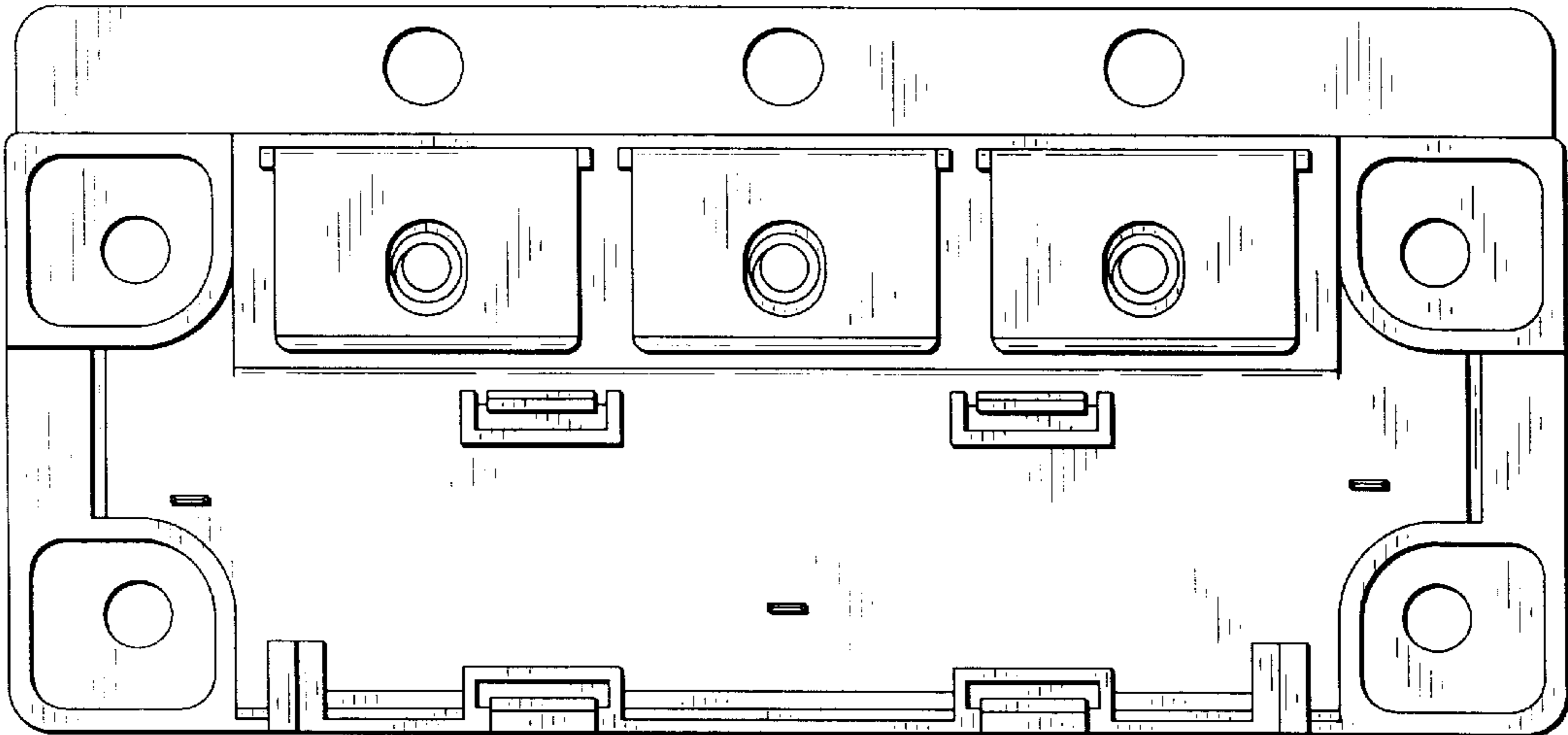


FIG. 4

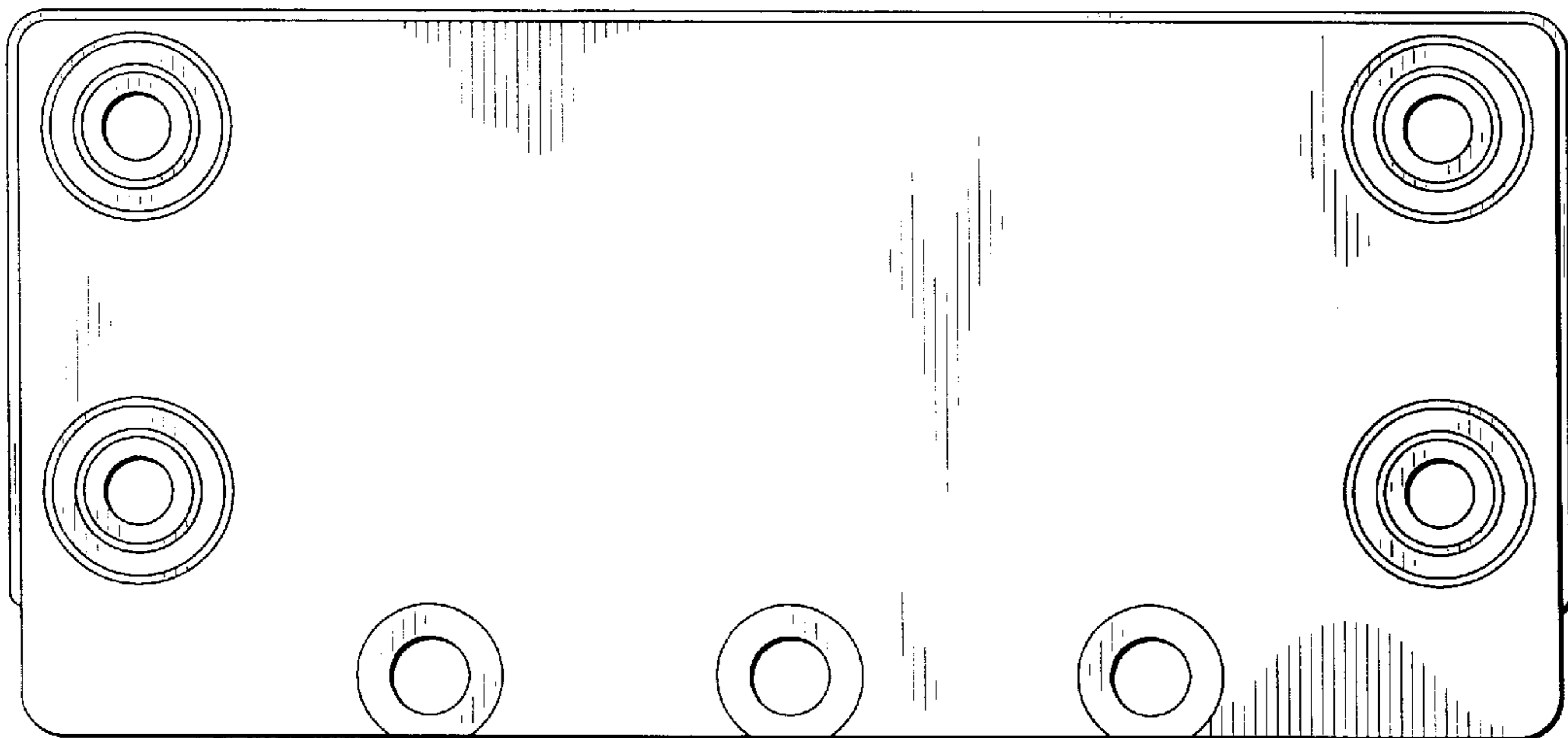


FIG. 5

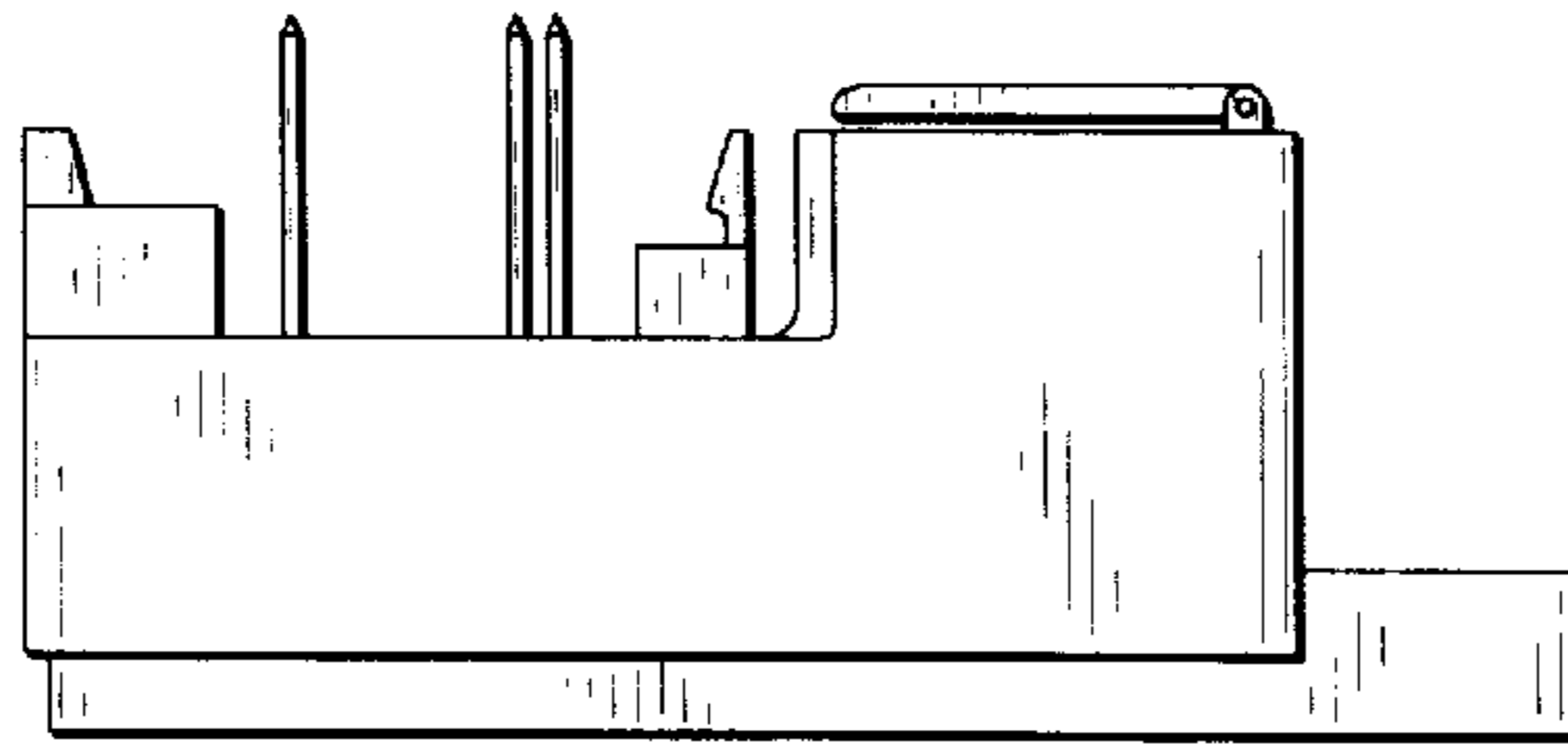


FIG. 6

